Chunqing Wang

List of Publications by Year in Descending Order

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220 papers	2,763 citations	27 h-index	40 g-index
331 ext. papers	3,495 ext. citations	3.8 avg, IF	5.41 L-index

#	Paper	IF	Citations
220	Revealing the ductile-to-brittle transition mechanism in polycrystalline body-centered tetragonal tin (Sn) for cryogenic electronics. *Journal of Alloys and Compounds*, **2022**, 903, 163948	5.7	0
219	Evolution of Wafer Bonding Technology and Applications from Wafer-Level Packaging to Micro/Nanofluidics-Enhanced Sensing **2022**, 187-215		
218	Rapid fabrication of Cu/40-µm thick full Cu3Sn/Cu joints by applying pulsed high frequency electromagnetic field for high power electronics. *Materials Chemistry and Physics*, **2022**, 276, 125386	4.4	1
217	Communication—Hollow MnO x @Nanoparticles Electrospun Fibers with High Porosity for Formaldehyde Removal at Room Temperature. *Journal of the Electrochemical Society*, **2022**, 169, 027518	3.9	
216	Ductile-to-brittle transition in fracture behaviors of common solder alloys over a temperature range down to -150 °C. *Materials Today Communications*, **2021**, 29, 102962	2.5	0
215	Superior Rate and Long-lived Performance of Few-Layered Black Phosphorus-Based Hybrid Anode for Lithium-Ion Batteries. *Electrochimica Acta*, **2021**, 403, 139697	6.7	1
214	Exposure to melamine cyanuric acid in adult mice induced thyroid dysfunction and circadian rhythm disorder. *Ecotoxicology and Environmental Safety*, **2021**, 228, 112992	7	0
213	Advances in the modification and device integration of multiferroic bismuth ferrite. *Ferroelectrics*, **2021**, 573, 87-102	0.6	0
212	Dissimilatory iron reduction and potential methane production in Chagan Lake wetland soils with carbon addition. *Wetlands Ecology and Management*, **2021**, 29, 369-379	2.1	2
211	Facile synthesis of Cu10Sn3 nanoparticles and their sintering behavior for power device packaging. *Results in Materials*, **2021**, 10, 100187	2.3	
210	Maximum shear stress-controlled uniaxial tensile deformation and fracture mechanisms and constitutive relations of Sn-Pb eutectic alloy at cryogenic temperatures. *Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing*, **2021**, 819, 141523	5.3	5
209	Preparation and sintering properties of Cu10Sn3 IMCs nanopaste as die attach material for high temperature power electronics. *Materials Letters*, **2021**, 282, 128845	3.3	1
208	Low-Temperature Co-hydroxylated Cu/SiO Hybrid Bonding Strategy for a Memory-Centric Chip Architecture. *ACS Applied Materials & Interfaces*, **2021**, 13, 38866-38876	9.5	6
207	Rapid pressureless and low-temperature bonding of large-area power chips by sintering two-step activated Ag paste. *Journal of Materials Science: Materials in Electronics*, **2020**, 31, 6497-6505	2.1	5
206	Recycled low-temperature direct bonding of Si/glass and glass/glass chips for detachable micro/nanofluidic devices. *Journal of Materials Science and Technology*, **2020**, 46, 156-167	9.1	10
205	Fabrication and characterization of silk fibroin coating on APTES pretreated Mg-Zn-Ca alloy. *Materials Science and Engineering C*, **2020**, 110, 110742	8.3	10
204	Electrodeposition fabrication of Cu@Ni core shell nanowire network for highly stable transparent conductive films. *Chemical Engineering Journal*, **2020**, 390, 124495	14.7	17

203	Unique buoyancy-force-based kinetics determination of beta to alpha phase transformation in bulk tin plates. *Materials and Design*, **2020**, 190, 108550	8.1	3
202	Microstructure characterization of Al2O3–Mullite–AlN multiphase ceramic film on Cr/WCu substrate. *Journal of Materials Science: Materials in Electronics*, **2020**, 31, 5941-5947	2.1	1
201	Investigation of Plasma Activation Directions for Low-Damage Direct Bonding. *ECS Journal of Solid State Science and Technology*, **2020**, 9, 081004	2	
200	Progress in wafer bonding technology towards MEMS, high-power electronics, optoelectronics, and optofluidics. *International Journal of Optomechatronics*, **2020**, 14, 94-118	3.5	10
199	Ohmic contact formation mechanisms of TiN film on 4H–SiC. *Ceramics International*, **2020**, 46, 7142-7148	5.1	3
198	Laser induced forward transfer of brittle Cu3Sn thin film. *Journal of Manufacturing Processes*, **2020**, 60, 48-53	5	0
197	Spontaneous formation of sub-4 nm nanocrystalline alloy via polymorphic phase transformation. *Materials Research Letters*, **2020**, 8, 431-437	7.4	0
196	Nanometer-Scale Heterogeneous Interfacial Sapphire Wafer Bonding for Enabling Plasmonic-Enhanced Nanofluidic Mid-Infrared Spectroscopy. *ACS Nano*, **2020**, 14, 12159-12172	16.7	22
195	High-efficiency extraction synthesis for high-purity copper nanowires and their applications in flexible transparent electrodes. *Nano Materials Science*, **2020**, 2, 164-171	10.2	13
194	Direct Heterogeneous Bonding of SiC to Si, SiO2, and Glass for High-Performance Power Electronics and Bio-MEMS **2019**,		2
193	Moir–Based Alignment Using Centrosymmetric Grating Marks for High-Precision Wafer Bonding. *Micromachines*, **2019**, 10,	3.3	2
192	Low-temperature direct bonding of Si and quartz glass using the APTES modification. *Ceramics International*, **2019**, 45, 16670-16675	5.1	7
191	Silk fibroin film-coated MgZnCa alloy with enhanced in vitro and in vivo performance prepared using surface activation. *Acta Biomaterialia*, **2019**, 91, 99-111	10.8	29
190	Laser sintering mechanism and shear performance of Cu–Ag–Cu joints with mixed bimodal size Ag nanoparticles. *Journal of Materials Science: Materials in Electronics*, **2019**, 30, 7787-7793	2.1	3
189	One-Step Fabrication of Copper Nanopillar Array-Filled AAO Films by Pulse Electrodeposition for Anisotropic Thermal Conductive Interconnectors. *ACS Omega*, **2019**, 4, 6092-6096	3.9	8
188	Chemical and thermal robust tri-layer rGO/Ag NWs/GO composite film for wearable heaters. *Composites Science and Technology*, **2019**, 174, 76-83	8.6	21
187	VUV/O3 activated direct heterogeneous bonding towards high-performance LiNbO3-based optical devices. *Applied Surface Science*, **2019**, 495, 143576	6.7	4
186	Pressureless low-temperature sintering of plasma activated Ag nanoparticles for high-power device packaging. *Materials Letters*, **2019**, 256, 126620	3.3	4

185	Fabrication of SiC/Si, SiC/SiO2, and SiC/glass heterostructures via VUV/O3 activated direct bonding at low temperature. *Ceramics International*, **2019**, 45, 4094-4098	5.1	18
184	A facile method for direct bonding of single-crystalline SiC to Si, SiO2, and glass using VUV irradiation. *Applied Surface Science*, **2019**, 471, 196-204	6.7	16
183	A novel cobalt-free CO2-stable perovskite-type oxygen permeable membrane. *Journal of Membrane Science*, **2019**, 573, 504-510	9.6	17
182	Low-temperature-solderable intermetallic nanoparticles for 3D printable flexible electronics. *Acta Materialia*, **2019**, 162, 163-175	8.4	15
181	Effect of electric current on grain orientation and mechanical properties of Cu-Sn intermetallic compounds joints. *Journal of Alloys and Compounds*, **2018**, 753, 203-211	5.7	18
180	Direct Homo/Heterogeneous Bonding of Silicon and Glass Using Vacuum Ultraviolet Irradiation in Air. *Journal of the Electrochemical Society*, **2018**, 165, H3093-H3098	3.9	18
179	Growth kinetics of CuSn intermetallic compound in Cu-liquid Sn interfacial reaction enhanced by electric current. *Scientific Reports*, **2018**, 8, 1775	4.9	18
178	Solderless bonding with nanoporous copper as interlayer for high-temperature applications. *Microelectronics Reliability*, **2018**, 80, 198-204	1.2	4
177	Room-Temperature Direct Heterogeneous Bonding of Glass and Polystyrene Substrates. *Journal of the Electrochemical Society*, **2018**, 165, B3091-B3097	3.9	2
176	Communication A Self-Contained Temperature Sensing Approach for Ultrafast Microwelding. *Journal of the Electrochemical Society*, **2018**, 165, B220-B222	3.9	4
175	Cohesively enhanced electrical conductivity and thermal stability of silver nanowire networks by nickel ion bridge joining. *Scientific Reports*, **2018**, 8, 5260	4.9	20
174	Robust tuning of Kirkendall void density in circuit interconnections through substrate strain annealing. *Journal of Materials Science: Materials in Electronics*, **2018**, 29, 8287-8292	2.1	
173	Mechanisms for low-temperature direct bonding of Si/Si and quartz/quartz VUV/O activation.. *RSC Advances*, **2018**, 8, 11528-11535	3.7	33
172	Glass-on-LiNbO3 heterostructure formed via a two-step plasma activated low-temperature direct bonding method. *Applied Surface Science*, **2018**, 459, 621-629	6.7	24
171	Communication Ag NW Networks Enhanced by Ni Electroplating for Flexible Transparent Electrodes. *Journal of the Electrochemical Society*, **2018**, 165, D328-D330	3.9	6
170	Low-temperature wafer direct bonding of silicon and quartz glass by a two-step wet chemical surface cleaning. *Japanese Journal of Applied Physics*, **2018**, 57, 02BD02	1.4	8
169	VUV/O3 activated bonder for low-temperature direct bonding of Si-based materials **2018**,		1
168	A Modified Interposer Fabrication Process by Copper Nano-Pillars Filled in Anodic Aluminum Oxide Film for 3D Electronic Package. *Applied Sciences (Switzerland)*, **2018**, 8, 2188	2.6	4

167	Communication□Defect-Free Direct Bonding for High-Performance Glass-On-LiNbO3 Devices. *Journal of the Electrochemical Society*, **2018**, 165, B727-B729	3.9	7
166	The Fabrication of Micro-Array Channels with the Ultrafine-Grained LZ91 Mg-Li Alloy by Micro-Embossing. *Micromachines*, **2018**, 9,	3.3	9
165	Recent Progress in Rapid Sintering of Nanosilver for Electronics Applications. *Micromachines*, **2018**, 9,	3.3	15
164	Direct bonding of silicon and quartz glass using VUV/O3 activation and a multistep low-temperature annealing process. *Applied Surface Science*, **2018**, 453, 416-422	6.7	21
163	Solid-State Spalling of Ag3Sn in an Eutectic SnPb Solder Joint with an Ag Thin Film/Ge Cell. *Journal of Electronic Materials*, **2018**, 47, 5625-5631	1.9	2
162	One-Step Fabrication of 3D Nanohierarchical Nickel Nanomace Array To Sinter with Silver NPs and the Interfacial Analysis. *ACS Applied Materials & Interfaces*, **2017**, 9, 4798-4807	9.5	10
161	Crystallized Bi 0.9 La 0.1 Fe 0.95 Mn 0.05 O 3 /Ba 0.7 Sr 0.3 Ti 0.95 Co 0.05 O 3 bilayer thin films with enhanced multiferroic properties. *Applied Surface Science*, **2017**, 404, 162-167	6.7	4
160	Laser-induced actuation of individual microsize liquid metal droplets on an open solid surface. *Applied Physics Express*, **2017**, 10, 017202	2.4	2
159	Fusion behaviour and mechanism of ultrafine Ag-Cu nanoparticles induced by electron beam irradiation. *Journal of Materials Science: Materials in Electronics*, **2017**, 28, 8206-8210	2.1	1
158	A Comparative Study: Void Formation in Silicon Wafer Direct Bonding by Oxygen Plasma Activation with and without Fluorine. *ECS Journal of Solid State Science and Technology*, **2017**, 6, P7-P13	2	18
157	Room-temperature direct bonding of silicon and quartz glass wafers. *Applied Physics Letters*, **2017**, 110, 221602	3.4	22
156	Laser Sintering of Nano-Ag Particle Paste for High-Temperature Electronics Assembly. *IEEE Transactions on Components, Packaging and Manufacturing Technology*, **2017**, 7, 1050-1057	1.7	4
155	Microstructure evolution and thermostability of bondline based on Cu@Sn core-shell structured microparticles under high-temperature conditions. *Materials and Design*, **2017**, 131, 196-203	8.1	22
154	Study of electroless Sn-coated Cu microparticles and their application as a high temperature thermal interface material. *Surface and Coatings Technology*, **2017**, 319, 230-240	4.4	11
153	Enhanced shear strength of Cu□Sn intermetallic interconnects with interlocking dendrites under fluxless electric current-assisted bonding process. *Journal of Materials Science*, **2017**, 52, 1943-1954	4.3	17
152	Low temperature nanojoining of silver□copper nanopaste as die attach material for high temperature packaging. *Journal of Materials Science: Materials in Electronics*, **2017**, 28, 5446-5451	2.1	4
151	Mechanical properties and fracture mechanisms of Sn-3.0Ag-0.5Cu solder alloys and joints at cryogenic temperatures. *Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing*, **2017**, 684, 697-705	5.3	23
150	Micro heat pipe device utilizing extended nanofluidics. *RSC Advances*, **2017**, 7, 50591-50597	3.7	8

149	Mechanisms for Room-Temperature Fluorine Containing Plasma Activated Bonding. *ECS Journal of Solid State Science and Technology*, **2017**, 6, P373-P378	2	15
148	Ultrafast formation of unidirectional and reliable Cu3Sn-based intermetallic joints assisted by electric current. *Intermetallics*, **2017**, 80, 26-32	3.5	18
147	Study on preparation and rapid laser sintering process of nano silver pastes **2017**,		1
146	Study on the pre-tinned effect in the electroless tin plating process **2017**,		1
145	Rapid sintering of copper nanopaste by pulse current for power electronics packaging **2017**,		2
144	Fuzzy Comprehensive Evaluation Model for Flight Safety Evaluation Research Based on an Empowerment Combination. *Advances in Intelligent Systems and Computing*, **2017**, 1479-1491	0.4	1
143	Preparation and Sintering Properties of Ag27Cu2Sn Nanopaste as Die Attach Material. *Journal of Electronic Materials*, **2016**, 45, 5436-5442	1.9	4
142	Extremely fast formation of CuSn intermetallic compounds in Cu/Sn/Cu system via a micro-resistance spot welding process. *Journal of Alloys and Compounds*, **2016**, 687, 667-673	5.7	36
141	The role of chloride ions in rapid synthesis of ultra-long silver nanowires for flexible electrodes. *Materials Research Express*, **2016**, 3, 075007	1.7	15
140	Communication□Fluorinated Plasma Treatments Using PTFE Substrates for Room-Temperature Silicon Wafer Direct Bonding. *ECS Journal of Solid State Science and Technology*, **2016**, 5, P393-P395	2	4
139	Effects of temperature and dispersants on the phases and morphology of Ag□Cu nanoparticles. *Journal of Materials Science: Materials in Electronics*, **2016**, 27, 10065-10069	2.1	7
138	Facile synthesis of Cu□Ag hybrid nanowires with strong surface-enhanced Raman scattering sensitivity. *CrystEngComm*, **2016**, 18, 1200-1206	3.3	15
137	Recent Progress in Ohmic Contacts to Silicon Carbide for High-Temperature Applications. *Journal of Electronic Materials*, **2016**, 45, 267-284	1.9	44
136	Optimization and modeling for one-step synthesis process of Ag□Cu nano-particles using DOE methodology. *Journal of Materials Science: Materials in Electronics*, **2016**, 27, 4265-4274	2.1	8
135	The influence of strengthening and recrystallization to the cracking behavior of Ni, Sb, Bi alloyed SnAgCu solder during thermal cycling. *Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing*, **2016**, 652, 264-270	5.3	21
134	TEM observation of interfacial compounds of SnAgCu/ENIG solder bump after laser soldering and subsequent hot air reflows. *Materials Letters*, **2016**, 163, 254-257	3.3	10
133	Interconnection of Cu wire/Au plating pads using parallel gap resistance microwelding process **2016**,		1
132	Degradation behaviors of micro ball grid array (□BGA) solder joints under the coupled effects of electromigration and thermal stress. *Journal of Materials Science: Materials in Electronics*, **2016**, 27, 11583-11592	2.1	7

131	Low-temperature bonding process for the fabrication of hybrid glass–membrane organ-on-a-chip devices. *Journal of Micro/ Nanolithography, MEMS, and MOEMS*, **2016**, 15, 044502	0.7	4
130	Sintering mechanism of the Cu–Ag core–shell nanoparticle paste at low temperature in ambient air. *RSC Advances*, **2016**, 6, 91783-91790	3.7	31
129	Effect of Cu grain size on the voiding propensity at the interface of SnAgCu/Cu solder joints. *Materials Letters*, **2015**, 144, 97-99	3.3	29
128	Fabrication of Al2O3–Mullite–AlN Multiphase Ceramic Layer on W–Cu Substrates for Power Semiconductor Packaging. *IEEE Transactions on Components, Packaging and Manufacturing Technology*, **2015**, 5, 182-187	1.7	5
127	Microstructures, corrosion and mechanical properties of as-cast Mg–Zn–Y–(Gd) alloys. *Transactions of Nonferrous Metals Society of China*, **2015**, 25, 2172-2180	3.3	38
126	Synthesis of CrO single crystal slices by firing under water vapor atmosphere. *Materials Letters*, **2015**, 152, 13-16	3.3	1
125	Electromigration-induced intermetallic growth and voids formation in symmetrical Cu/Sn/Cu and Cu/Intermetallic compounds (IMCs)/Cu joints. *Journal of Materials Science: Materials in Electronics*, **2015**, 26, 2674-2681	2.1	19
124	Effect of the Silver Content of SnAgCu Solder on the Interfacial Reaction and on the Reliability of Angle Joints Fabricated by Laser-Jet Soldering. *Journal of Electronic Materials*, **2015**, 44, 733-743	1.9	4
123	Rapid formation of full Cu-In intermetallic compounds (IMCs) joints under electric current **2015**,		1
122	Microstructures and Properties of As-Cast Mg92Zn4Y4 and Mg92Zn4Y3Gd1 Alloys with LPSO Phase. *Rare Metal Materials and Engineering*, **2015**, 44, 1617-1622		5
121	The influence of high melting point elements on the reliability of solder during thermal shocks **2015**,		1
120	Joining of Silver Nanowires by Femtosecond Laser Irradiation Method. *Materials Transactions*, **2015**, 56, 981-983	1.3	8
119	Low Temperature Sintering Cu6 Sn5 Nanoparticles for Superplastic and Super-uniform High Temperature Circuit Interconnections. *Small*, **2015**, 11, 4097-103	11	38
118	The investigation of quality of life in 87 Chinese patients with disorders of sex development. *BioMed Research International*, **2015**, 2015, 342420	3	10
117	In situ quantitative study of microstructural evolution at the interface of Sn3.0Ag0.5Cu/Cu solder joint during solid state aging. *Journal of Alloys and Compounds*, **2015**, 634, 94-98	5.7	14
116	Characterization of the Microstructure of an AlN-Mullite-Al2O3 Ceramic Layer on WCu Composite Alloy for Microelectronic Application. *Journal of Electronic Materials*, **2015**, 44, 4154-4160	1.9	3
115	Suppression of void nucleation in Sn3.0Ag0.5Cu/CU solder joint by rapid thermal processing. *Materials Letters*, **2015**, 158, 252-254	3.3	4
114	Effect of Au-Sn IMCs–formation and morphologies on shear properties of laser reflowed micro-solder joints. *Soldering and Surface Mount Technology*, **2015**, 27, 45-51	1.4	18

113	Research and analysis of central heating systems in Changchun **2015**, 161-165		
112	Design and simulation research of Ground Source Heat Pump system in severe cold regions **2015**, 157-160		
111	Relationship between morphologies and orientations of Cu6Sn5 grains in Sn3.0Ag0.5Cu solder joints on different Cu pads. *Materials Characterization*, **2014**, 88, 58-68	3.9	46
110	Cu nanoparticles of low polydispersity synthesized by a double-template method and their stability. *Colloid and Polymer Science*, **2014**, 292, 715-722	2.4	14
109	Effects of ultrasonic irradiation and cooling rate on the solidification microstructure of Sn3.0Ag0.5Cu alloy. *Journal of Materials Processing Technology*, **2014**, 214, 13-20	5.3	17
108	Phase transformation and fracture behavior of Cu/In/Cu joints formed by solid–liquid interdiffusion bonding. *Journal of Materials Science: Materials in Electronics*, **2014**, 25, 4170-4178	2.1	18
107	Effects of Ba0.7Sr0.3TiO3-based buffer layers and La/Mn doping on the crystallization behavior and multiferroic properties of BiFeO3 thin films. *RSC Advances*, **2014**, 4, 55889-55896	3.7	5
106	Ultrafine-Grain and Isotropic Cu/SAC305/Cu Solder Interconnects Fabricated by High-Intensity Ultrasound-Assisted Solidification. *Journal of Electronic Materials*, **2014**, 43, 2467-2478	1.9	17
105	Ultrarapid formation of homogeneous Cu6Sn5 and Cu3Sn intermetallic compound joints at room temperature using ultrasonic waves. *Ultrasonics Sonochemistry*, **2014**, 21, 924-9	8.9	37
104	Parallel-gap resistance welding between gold-plated silver interconnects and silver electrodes in germanium solar cells **2014**,		1
103	Rapid formation of Cu-Sn intermetallic compounds by strong electric current **2014**,		1
102	Secondary optical design of LED lamps with high CRI and adjustable CCT **2014**,		1
101	Fabrication of Cu6Sn5 single-crystal layer for under-bump metallization in flip-chip packaging. *Intermetallics*, **2013**, 42, 52-55	3.5	8
100	Shear Deformation Behaviors of Sn3.5Ag Lead-free Solder Samples. *Journal of Materials Science and Technology*, **2013**, 29, 471-479	9.1	7
99	Formation mechanism and orientation of Cu3Sn grains in Cu–Sn intermetallic compound joints. *Materials Letters*, **2013**, 110, 137-140	3.3	54
98	Synthesis of multiferroic Bi0.9La0.1Fe0.95Mn0.05O3–Ba0.7Sr0.3TiO3–Ni0.8Zn0.2Fe2O4 nanotubes with one closed end using a template-assisted sol–gel process. *CrystEngComm*, **2013**, 15, 2147	3.3	11
97	Formation of AuSnx IMCs in Sn3.5Ag0.75Cu micro-solder joints fabricated by laser and hot air reflow processes. *Journal of Materials Science: Materials in Electronics*, **2013**, 24, 217-223	2.1	4
96	Rapid pressureless low-temperature sintering of Ag nanoparticles for high-power density electronic packaging. *Scripta Materialia*, **2013**, 69, 789-792	5.6	102

95	Electrochemical synthesis of Ni–S/CeO2 composite electrodes for hydrogen evolution reaction. *Journal of Power Sources*, **2013**, 230, 10-14	8.9	33
94	Multiferroic properties of La and Mn co-doped BiFeO3 nanofibers by sol–gel and electrospinning technique. *Materials Letters*, **2013**, 90, 45-48	3.3	57
93	Fabrication of multiferroic Ba0.7Sr0.3TiO3–Ni0.8Zn0.2Fe2O4 composite nanofibers by electrospinning. *Materials Letters*, **2013**, 91, 55-58	3.3	14
92	Rapid formation of Cu/Cu3Sn/Cu joints using ultrasonic bonding process at ambient temperature. *Applied Physics Letters*, **2013**, 102, 094104	3.4	58
91	Manufacturing and Microstructure of Cu Coated Diamonds/SnAgCu Composite Solder Bumps. *Applied Mechanics and Materials*, **2013**, 288, 323-327	0.3	1
90	Surface-Tension-Driven Self-Assembly of 3-D Microcomponents by Using Laser Reflow Soldering and Wire Limiting Mechanisms. *IEEE Transactions on Components, Packaging and Manufacturing Technology*, **2013**, 3, 168-176	1.7	5
89	Molecular Dynamics study of thermal conductivity in bismuth telluride thin films **2013**,		1
88	The effects of humidity and temperature aging test on flexible packaging LED module **2013**,		4
87	RESEARCH ON MICROSTRUCTURE OF Pb-FREE BGASOLDER JOINT ASSEMBLED WITH Sn-Pb SOLDERDURING ISOTHERMAL AGING. *Jinshu Xuebao/Acta Metallurgica Sinica*, **2013**, 49, 831		2
86	Precision Study for Surface Tension Driven Self-assembly of Hingeless Structures. *Journal of Applied Sciences*, **2013**, 13, 2807-2812	0.3	
85	Synthesis of Co-doped barium strontium titanate nanofibers by sol–gel/electrospinning process. *Materials Letters*, **2012**, 75, 207-210	3.3	12
84	Investigation of fluorine containing plasma activation for room-temperature bonding of Si-based materials. *Microelectronics Reliability*, **2012**, 52, 347-351	1.2	20
83	Mechanical properties and microstructures of hybrid ultrasonic resistance brazing of WC-Co/BeCu. *Journal of Materials Processing Technology*, **2012**, 212, 1885-1891	5.3	14
82	Effect of intermetallic compounds on fracture behaviors of Sn3.0Ag0.5Cu lead-free solder joints during in situ tensile test. *Journal of Materials Science: Materials in Electronics*, **2012**, 23, 136-147	2.1	16
81	Oxidation and Au-Sn reaction of laser reflowed micro-solder joints protected by N2 or exposed to air atmosphere. *Soldering and Surface Mount Technology*, **2012**, 24, 191-196	1.4	6
80	Ultrasonic Bondability and Antioxidation Property of Ti/Cu/TaN/Ag Multi-layers on Si Substrate. *Thin Solid Films*, **2012**, 524, 224-228	2.2	4
79	The effect of voids on thermal conductivity of solder joints **2012**,		5
78	Mechanism of low temperature Cu-In Solid-Liquid Interdiffusion bonding in 3D package **2012**,		7

77	Fabrication of interconnects using pressureless low temperature sintered Ag nanoparticles. *Materials Letters*, **2012**, 85, 61-63	3.3	53
76	Morphologies and grain orientations of CuSn intermetallic compounds in Sn3.0Ag0.5Cu/Cu solder joints. *Materials Letters*, **2012**, 86, 157-160	3.3	21
75	Interfacial reactions of eutectic Sn3.5Ag and pure tin solders with Cu substrates during liquid-state soldering. *Intermetallics*, **2012**, 25, 86-94	3.5	42
74	Effect of Diamond Additions on Wettability and Distribution of SnAgCu Composite Solder. *Journal of Materials Science and Technology*, **2012**, 28, 661-665	9.1	10
73	NiCeO2 composite cathode material for hydrogen evolution reaction in alkaline electrolyte. *International Journal of Hydrogen Energy*, **2012**, 37, 13921-13932	6.7	76
72	Solar Water Heating System and Building Integration of High-Rise Building in Seismic Zone. *Advanced Materials Research*, **2012**, 512-515, 163-167	0.5	
71	Prediction of Municipal Solid Waste Production in Changchun City Based on Gray Model GM(1,5). *Applied Mechanics and Materials*, **2012**, 178-181, 799-803	0.3	2
70	Effect of grain orientation on electromigration degradation in lead-free solder joints **2012**,		1
69	The Process Optimization of EFO for Copper Wire Bonding. *Advanced Materials Research*, **2012**, 482-484, 763-766	0.5	
68	Effects of bump size on deformation and fracture behavior of Sn3.0Ag0.5Cu/Cu solder joints during shear testing. *Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing*, **2011**, 529, 468-478	5.3	40
67	Reliability and failure analysis of fine copper wire bonds encapsulated with commercial epoxy molding compound. *Microelectronics Reliability*, **2011**, 51, 157-165	1.2	26
66	Development of a three-dimensional integrated solder ball bumping & bonding method for MEMS devices **2011**,		2
65	Analysis of Cu6Sn5 grain orientations in Sn3.0Ag0.5Cu lead-free solder joints **2011**,		1
64	Self-assembly of three-dimensional microstructures in MEMS via fluxless laser reflow soldering **2011**,		1
63	Room-Temperature Direct Bonding Using Fluorine Containing Plasma Activation. *Journal of the Electrochemical Society*, **2011**, 158, H525	3.9	14
62	Ultrasonic bondability and antioxidation property of Ti/Cu/Ag metallization on Si substrate **2010**,		1
61	Investigation on Sn grain number and crystal orientation in the SnAgCu/Cu solder joints of different sizes. *Journal of Materials Science: Materials in Electronics*, **2010**, 21, 1174-1180	2.1	21
60	MICROSTRUCTURE AND RELIABILITY OF LASER JET SOLDER BALL BONDING SOLDER JOINTS. *Jinshu Xuebao/Acta Metallurgica Sinica*, **2010**, 46, 1115-1120		2

59	ULTRASONIC BONDABILITY AND ANTIOXIDATION PROPERTY OF TiN/Ag METALLIZATION ON Cu PAD. *Jinshu Xuebao/Acta Metallurgica Sinica*, **2010**, 46, 618-622		
58	Modeling of an oblique impact of solder droplet onto a groove with the impact point to be offset from the groove surfaces interface. *Journal of Materials Science*, **2009**, 44, 1772-1779	4.3	1
57	Effect of electronic flame off parameters on copper bonding wire: Free-air ball deformability, heat affected zone length, heat affected zone breaking force. *Microelectronic Engineering*, **2009**, 86, 2094-2103	2.5	25
56	In situ measurement of bond resistance varying with process parameters during ultrasonic wedge bonding. *Journal of Materials Processing Technology*, **2009**, 209, 139-144	5.3	3
55	Shape and fatigue life prediction of chip resistor solder joints **2009**,		2
54	Modeling thermal fatigue in anisotropic Sn-Ag-Cu/Cu solder joints **2009**,		3
53	Modeling of Micropitch Shift of a Magnetoelectrical Sensor During Laser Solder Ball Bonding Process. *IEEE Transactions on Advanced Packaging*, **2009**, 32, 136-145		2
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51	Investigation of sagging phenomenon observed in laser reflow soldering right-angled solder joints during isothermal aging or thermal cycle process. *Journal of Alloys and Compounds*, **2008**, 458, 323-329	5.7	2
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